

**PATENT ASSIGNMENT**

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Chi-Min Yu	05/20/2007
Chi-Chih Chuang	05/20/2007
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	UNITED MICROELECTRONICS CORP.
<b>Street Address:</b>	No.3, Li-Hsin Road 2, Science-Based Industrial Park
<b>City:</b>	Hsin-Chu City
<b>State/Country:</b>	TAIWAN
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	11752928
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(703)997-4517
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
<b>Phone:</b>	3027291562
<b>Email:</b>	Patent.admin.uspto.cr@naipo.com
<b>Correspondent Name:</b>	WINSTON HSU
<b>Address Line 1:</b>	P.O.BOX 506
<b>Address Line 4:</b>	Merrifield, VIRGINIA 22116
<b>ATTORNEY DOCKET NUMBER:</b>	NAUP0914USA
<b>NAME OF SUBMITTER:</b>	WINSTON HSU
<b>Total Attachments: 2</b>	
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CH \$40.00 11752928

**ASSIGNMENT OF INVENTION**

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

**ASSIGNOR(S) (Inventors):**

Name: Chi-Min Yu Nationality: R.O.C.

Name: Chi-Chih Chuang Nationality: R.O.C.

Hereby sells, assigns and transfers to

**ASSIGNEE(S):**

Name: UNITED MICROELECTRONICS CORP.

Address: No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"CMP HEAD AND METHOD OF MAKING THE SAME"

Which is found in :

- (a) + U.S. patent application executed on even date  
 (b) \_\_\_\_\_ U.S. patent application executed on \_\_\_\_\_  
 (c) \_\_\_\_\_ U.S. application serial no. \_\_\_\_\_  
 (d) \_\_\_\_\_ patent no. \_\_\_\_\_ issued \_\_\_\_\_

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this MAY 20 2007 (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Signature of INVENTOR

Chi-Min Yu

Chi-Min Yu

Chi-Chih Chuang

Chi-chih Chuang